| ABSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>INTERNATIONAL AND A TRIES | IPC, Bannock  | burn, Illinois. A         | ll rights reserved untions. | nder both           | This docum<br>level parts, t | ent is a decla<br>the declaratio                                | ration of the | substances<br>ses all lowe | within the materia          | nufacturer lis<br>als for which t | ted item.<br>he manut              | Note: if th<br>facturer ha | he item is an ass<br>as engineering i | sembly with lower<br>responsibility. |  |
|--|---|---------------------------|-----------------------------|---------------------|------------------------------|---|---------------|----------------------------|-----------------------------|-----------------------------------|------------------------------------|----------------------------|---------------------------------------|--------------------------------------|--|
|  | IPC Web Site for Information on IPC-1752 Standard Form Type<br>http://www.ipc.org/IPC-175x Distribute |                           |                             |                     | *                            | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |               |                            |                             |                                   | als and Mfg Information            |                            |                                       |                                      |  |
| Supplier Information   |   |                           |                             |                     |                              |   |               |                            |                             |                                   |                                    |                            |                                       |                                      |  |
| Company name*  |   |                           | Company unique ID           |                     |                              | Unique ID Authority   |               |                            |                             |                                   | Response Date*                     |                            |                                       |                                      |  |
| onsemi   |   |                           |                             |                     |                              |   |               |                            |                             |                                   | 2024-05-19                         |                            |                                       |                                      |  |
| Contact Name Title - Co  |   |                           | Contact                     |                     |                              | Phone - Contact*  |               |                            |                             | Em                                | Email - Contact*                   |                            |                                       |                                      |  |
| Product-Env-Stewards Pro   |   |                           | Product Enviro Compliance   |                     |                              | NA  |               |                            |                             | Pro                               | Product-Env-Stewards@onsemi.com    |                            |                                       |                                      |  |
| Authorized Representative* Title   |   |                           | Fitle - Representative      |                     |                              | Phone - Representative*   |               |                            |                             | Em                                | Email - Representative*            |                            |                                       |                                      |  |
| Product-Env-Stewards   | Product Envir   | Product Enviro Compliance |                             |                     | NA                           |   |               |                            | Pro                         | Product-Env-Stewards@onsemi.com   |                                    |                            |                                       |                                      |  |
| Requester Item Number  | Mfr Iten  | n Number                  | Mfr Item Name               |                     |                              | Effective D   | ate Versio    | n :                        | Manufacturing Site          |                                   | Weig                               | ght*                       | UOM                                   | Unit Type                            |  |
|  | NLVLV   | NLVLVX4245DTR2G LOG 8BI   |                             | OG 8BIT DUAL SUPPLY |                              | 2024-05-19  |               |                            | PH1                         |                                   | 69.68                              | 3                          | mg                                    | Each                                 |  |
| Manufacturing Proccess Informa   | ation   |                           |                             |                     |                              |   |               |                            |                             |                                   |                                    |                            | 1                                     |                                      |  |
| Terminal Plating / Grid Array M  | Iaterial 7  | Ferminal Base A           | Alloy J                     | -STD-020 MSL Rating |                              | Peak Process Body Te  |               | Temperatu                  | perature Max Time at Peak T |                                   | emperature Number of Reflow Cycles |                            | les                                   |                                      |  |
| Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)                                    |   | CU Alloy 1                |                             | l                   |                              | 260   |               | С                          | 30 seco                     |                                   | econds                             | conds 3                    |                                       |                                      |  |
| Comments   |   |                           |                             |                     |                              |   |               |                            |                             |                                   |                                    |                            |                                       |                                      |  |
| evel 1 - maximum time at peak temperat   | ture during so  | Idering is 10-3           | 0 seconds                   |                     |                              |   |               |                            |                             |                                   |                                    |                            |                                       |                                      |  |
| for more information regarding materia   | l composition   | please refer to           | page 3                      |                     |                              |   |               |                            |                             |                                   |                                    |                            |                                       |                                      |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

|                      | cable [E] enter the weigh |                 |          | ance category (JIG or Requester) or enter<br>[F] Optionally enter the positive (+) ar |                  |        |         |                 |
|----------------------|---------------------------|-----------------|----------|---|------------------|--------|---------|-----------------|
| Homogeneous Material | Weight                    | Unit of Measure | Level    | Substance   | CAS              | Exempt | Weight  | Unit of Measure |
| Die                  | 3.12                      | mg              | Supplier | Silicon (Si)  | 7440-21-3        |        | 3.12    | mg              |
| Die Attach           | 1.26                      | mg              | Supplier | Silver (Ag)   | 7440-22-4        |        | 0.945   | mg              |
|                      |                           |                 | Supplier | Epoxy resins  | 129915-35-1      |        | 0.315   | mg              |
| Lead Frame           | 16.21                     | mg              | Supplier | Iron (Fe)   | 7439-89-6        |        | 0.308   | mg              |
|                      |                           |                 | Supplier | Copper (Cu)   | 7440-50-8        |        | 15.902  | mg              |
| Mold Compound-Black  | 45.76                     | mg              |          | Epoxy Phenol Resin  | proprietary data |        | 4.8048  | mg              |
|                      |                           |                 | Supplier | Fused Silica (SiO2)   | 60676-86-0       |        | 40.9552 | mg              |
| Plating              | 2.91                      | mg              | Supplier | Palladium (Pd)  | 7440-05-3        |        | 0.2212  | mg              |
|                      |                           |                 | В        | Nickel (Ni)   | 7440-02-0        |        | 2.6481  | mg              |
|                      |                           |                 | Supplier | Gold (Au)   | 7440-57-5        |        | 0.0407  | mg              |
| Wire Bond - Au       | 0.42                      | mg              | Supplier | Gold (Au)   | 7440-57-5        |        | 0.42    | mg              |